

PCB SPECIFICATIONS :

A. MATERIAL :

FR-4

☐ TG-170

☒ TG-150

☐ TG-140

B. MATERIAL FAMILY :

N/A

C. SOLDERMASK COLOR :

☐ GREEN

☒ BLUE

☐ RED

☐ BLACK

D. SILKSCREEN COLOR :

☒ WHITE

☐ YELLOW

☐ BLACK

E. SURFACE FINISH :

☒ ENIG

☐ IMMERSION SILVER

☐ IMMERSION TIN

☐ HASL

☐ HASL (PB-FREE)

☐ GOLDEN FINGER

F. IMPEDANCE CONTROL :

☐ NO

☒ YES (SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)

G. THROUGH VIA :

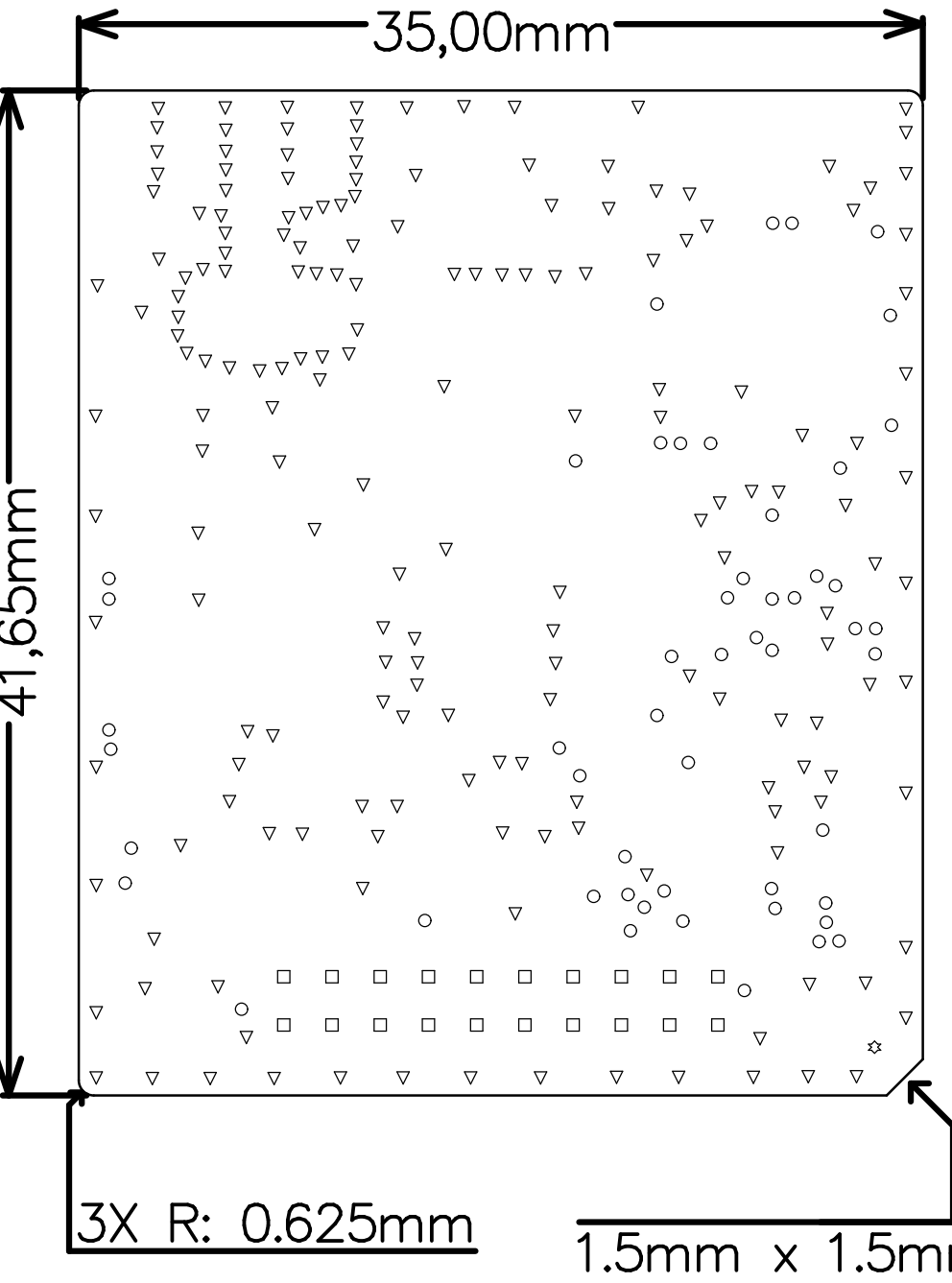
PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.

PLUG MATERIAL : ☒ SOLDERMASK

☐ NON-CONDUCTIVE EPOXY.

H. STACK-UP :

SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.



Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0,015mm	4	
3	Top Layer	Copper	0,042mm		
4	Dielectric 1		0,095mm	4,2	
5	Signal Layer 1	Copper	0,035mm		
6	Dielectric 2		1,130mm	4,3	
7	Signal Layer 2	Copper	0,035mm		
8	Dielectric 3		0,095mm	4,2	
9	Bottom Layer	Copper	0,042mm		
10	Bottom Solder	Solder Resist	0,015mm	4	
11	Bottom Overlay				

MINIMUM PARAMETERS
DEFAULT TRACKS : 0.200mm GAPS : 0.200mm
PAIRE DIFF. USB TRACKS : 0.100mm GAPS : 0.160mm

Symbol	Count	Hole Size	Plated	Hole Type	Via/Pad
☆	1	1,500mm (59,06mil)	NPTH	Round	Pad
□	20	0,900mm (35,43mil)	PTH	Round	Pad
○	52	0,200mm (7,87mil)	PTH	Round	Via
▽	185	0,300mm (11,81mil)	PTH	Round	Via
	258 Total				

IMPEDANCE TABLE					
LAYER	TRACE (mm)	SPACING (mm)	IMPEDANCE (Single ended)	IMPEDANCE (Differentiel)	TOL.
Signal Layer 2 (L3)	0.100	0.160	NA	90 ohm	+/- 10%

 life.augmented
<http://www.st.com>
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LAYER :

FAB DRAWING & DRILL LEGEND

DESIGNER : STM

DATE : 2017.07.11

COMPANY NAME :

STMicroelectronics

PROJECT NAME :

STM32–SISM

PROJECT NUMBER :

MB1329

REV

B